



Material Content Data Sheet



Halogen-Free

Sales Product Name	TLE7257SJ	Issued	24. February 2022
MA#	MA005708044		
Package	PG-DSO-8-44	Weight*	82.63 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.828	1.00	1.00	10019	10019
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		434	
	non noble metal	iron	7439-89-6	0.717	0.87		8679	
	non noble metal	copper	7440-50-8	29.121	35.24	36.16	352415	361636
wire	non noble metal	copper	7440-50-8	0.061	0.07	0.07	733	733
encapsulation	organic material	carbon black	1333-86-4	0.100	0.12		1212	
	plastics	epoxy resin	-	4.606	5.57		55740	
	inorganic material	silicondioxide	60676-86-0	45.359	54.91	60.60	548918	605870
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9849	9849
plating	noble metal	silver	7440-22-4	0.650	0.79	0.79	7869	7869
glue	plastics	acrylic resin	-	0.073	0.09		885	
	noble metal	silver	7440-22-4	0.259	0.31	0.40	3139	4024
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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